# MA27D27

## Silicon epitaxial planar type

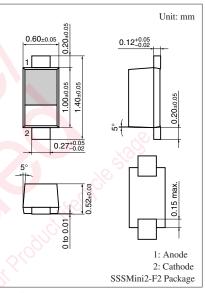
For super high speed switching

#### Features

- Small reverse current I<sub>R</sub>
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>
- SSS-Mini type 2-pin package

Absolute Maximum Matings $T_a = 25$ C						
Parameter	Symbol	Rating	Unit			
Reverse voltage	V <sub>R</sub>	20	v			
Repetitive peak reverse voltage	V <sub>RRM</sub>	20	V			
Forward current (Average)	I <sub>F(AV)</sub>	100	mA			
Peak forward current	I <sub>FM</sub>	200	mA			
Non-repetitive peak forward	I <sub>FSM</sub>	1	А			
surge current *						
Junction temperature	Tj	150	°C			
Storage temperature	T <sub>stg</sub>	-55 to +150	°C			





Marking Symbol: 8L

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

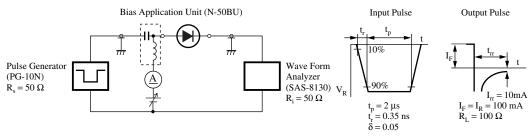
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F1</sub>	$I_F = 10 \text{ mA}$	0	0.38	0.44	V
	V <sub>F2</sub>	I <sub>F</sub> = 100 mA	je v	0.54	0.58	
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 10 V	$\sim 2^{\circ}$		0.3	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 0 V, f = 1 MHz$		11		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

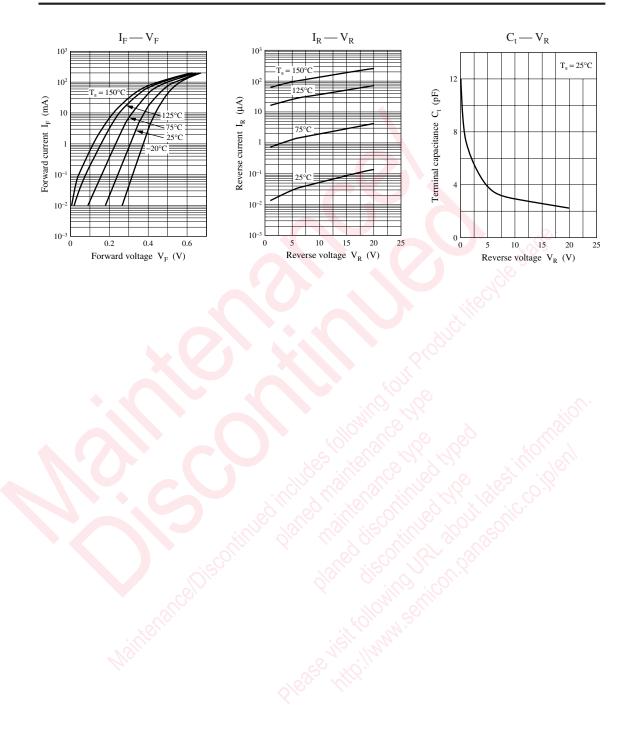
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Rated input/output frequency: 250 MHz
- 4.  $*: t_{rr}$  measurement circuit



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